

FPC用压延铜箔 (GHY5处理箔)

Rolled Copper Foil for Flexible Printed Circuit(GHY5 Treatment Foil)

- 新规压延铜箔(GHY5处理箔)和现行的标准压延铜箔(Y处理箔)相比, 实现了粗化粒子的超细微化、箔表面的超低粗度
New RA copper foil (GHY5 Treatment Foil) has super fine nodules and the lowest surface roughness compared with that of regular Y Treatment RA Foil
- FFCL的铜箔蚀刻除去后, 实现PI(聚酰亚胺)膜基板的高透明性。
With this new RA foil,excellent PI (polyimide) film transparency can be obtained after removal of copper foil etching of FCCL.
- 多层基板的FPC位置准线工序中发挥优异可清晰可视效果。
Superior Visibility performance can be achieved for alignment process for multi-layer FPC.

